



Serial No. 09/920,713

IIZ.003D2

Amendment dated October 16, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 09/920,713

Examiner: F. Toledo

Filed: August 3, 2001

For: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

AMENDMENT UNDER 37 C.F.R. 1.116

U.S. Patent and Trademark Office
2011 South Clark Place
Customer Window, **Mail Stop AF**
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Date: October 16, 2003

Sir:

In response to the Final Office Action dated April 17, 2003, the period for response having been extended three (3) months to October 17, 2003, and further responsive to the Advisory Action dated October 3, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

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Remarks/Arguments begin on page 6 of this paper.